

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Original) An aerogel molded part containing a filler containing inorganic hollow spheres and having a thermal conductivity of up to $0.5 \text{ Wm}^{-1}\text{K}^{-1}$.
2. (Currently Amended) The aerogel molded part according to claim 1, ~~characterized in that~~ wherein said aerogel is ~~[[a]] selected from the group consisting essentially of silica aerogel aerogels, [[a]] carbon aerogel aerogels, or an organic aerogel aerogels, especially a resorcinol/formaldehyde aerogel or combinations thereof.~~
3. (Currently Amended) The aerogel molded part according to claim 1, ~~characterized in that~~ wherein said hollow spheres consist of glass.
4. (Currently Amended) The aerogel molded part according to claim 1, ~~characterized in that~~ wherein the thermal conductivity of the filler is up to $0.1 \text{ Wm}^{-1}\text{K}^{-1}$.
5. (Currently Amended) The aerogel molded part according to claim 1, ~~characterized in that~~ wherein said aerogel contains a filler in an amount of from about 70% to 90% by volume.

6. (Currently Amended) The aerogel molded part according to claim 1, ~~characterized in that~~ wherein the thermal conductivity of the molded part is lower than the thermal conductivity of the filler-free aerogel.

7. (Currently Amended) A process for the preparation of an aerogel molded part according to ~~any of claims 1 to 6~~ claim 1, comprising the following steps of:

- a. preparation of a sol;
- b. mixing the sol with a filler;
- c. gelling of the sol into a gel; and
- d. drying of the gel.

8. (Currently Amended) The process according to claim 7, ~~characterized in that~~ wherein the resulting aerogel molded part is pyrolyzed.